

19th ASEMEP NATIONAL TECHNICAL SYMPOSIUM



Achieving Limitless
Possibilities with
an Enabled
Engineering

Workforce

19th ANTS Host Company



Organized By:



A Project Of:



ANTS 2009

ASEMEP NATIONAL TECHNICAL SYMPOSIUM

Event Program (Opening Ceremonies)

DAY 1: Thursday, 04 June 2009

08:00AM	Registration & Morning Snack	10:30AM	Academe: Dr. Reynaldo Vea President / MAPUA
09:00AM	Invocation	11:00AM	Government: Hon. Joseph Emilio Abaya Philippine House of Representative Committee on Science & Technology
09:05AM	National Anthem: AVP		
09:10AM	ASEMEP AVP		
09:15AM	Welcome Remarks: Mr. Luke Mendoza ASEMEP Chairman	11:30AM	IMI AVP
09:25AM	Key Note Address: Mr. Art Tan IMI President and CEO	11:35AM	IMI Technical Presentation Mr. Tim Patterson Managing Director, Advanced Manufacturing Engineering
09:45AM	Induction of New Set of ASEMEP BOD & COP Chairmen	12:05NN	IMI ISO 17025 Certification Awarding
10:00AM	Plenary Speeches: Industry: Mr. Arthur Young Jr. SEIPI Chairman	12:15PM	Turnover Ceremonies Next ANTS Host: NXP Semiconductor Cabuyao
		12:25PM	LUNCH

DAY 1: ANTS
Thursday, 04 June 2009

TIME	SESSION A SMX Meeting Room 2&3	SESSION B SMX Meeting Room 4&5	SESSION C SMX Meeting Room 6	SESSION D SMX Meeting Room 8&9	SESSION E SMX Meeting Room 7
	SEMICONDUCTOR MANUFACTURING SYSTEM	PRODUCT & TEST TECHNOLOGY	ELECTRONICS MANUFACTURING SYSTEM	QUALITY SYSTEM, FA & REL	QUALITY SYSTEM, FA & REL / SUPPORT SYSTEMS FACILITIES
	Moderators: Dr. Celso Co Dr. Rafi Delica	Moderators : Dr. Terence Lacuesta Rico Del Moro	Moderators : Olsen Bandehala Edwin Salido	Moderators : Dr. Leon Payawan Ronald Hilaria	Moderators : Ridor Dacasin Rochelly Martinez
130 PM	Delamination Reduction Via Wirebond Nitrogen Purging: Effective Method In Reducing Oxidation Growth On Cu-Based Leadframe NXP Nico L. Labatete Ken Ryner H. So	TIXs Universal Test Hardware Cypress Adrian A. Dionisio	Process Capability Improvement Project In Optical Pick-up Assembly IMI Jeffrey M. De Sembrana	A New Bond Pad Material Design and Structure To Eliminate Wirebond Ball Lift In Opto-Isolator Package Using Low Temperature Ultrasonic (US) Wirebonding VISHAY Arnold Y. Umali Joseph C. Mamauag Ariel P. Canton	Reduction Of Water Treatment Plant Operation Cost Through Increasing The Efficiency Of Reverse Osmosis Membrane Cleaning System Toshiba Mirasol G. Gabutero Romel C. Clarito Ireneo F. Cana Jr.
200 PM	Enhanced Contamination Removal System: A Solution To Foreign Material on Bar Reduction TIPI Pablo Remogat Jr Roderick Castor Sammy Tan	Die Tilt Determination by 3D Vectorization of Height Data From Confocal Laser Sensor Measurements IMI Bernardino J. Buenaobra	484ZED Package Qualification Success - Leading The Way To New Packaging and Reliability Advancements on Plastic BGA Devices TIPI Sammy C. Gamuza Emory M. Mercado Ferdie S. Signey	Six Sigma DMAIC Approach: A Way Of Life In Process Yield Improvement IMI Dickson O. Raymundo	Elimination of Trim Form Parts In-House Inspection Quality Control Via Ship-to-Line Program - A System Integrating "Quality at Source" ST Microelectronics Jeric G. Oyong Elgina C. Lim Marife D. Quiambao
230 PM	Transmission Electron Microscopy Analysis of Gold-Assisted MBE Grown Gallium Arsenide Nanowires on Silicon Substrates UP Diliman Condensed Matter Physics Laboratory (CMPL)- National Institute of Physics (NIP)	Simple Approach In Grounded Down- Bond Testing Cypress John Patrick R. Gabuya Melvin A. Damot	Elimination Of Disc Can't Insert Problem In Optical Disc Drive Assembly Line IMI Isagani M. Valerio	Mode I Popcorn Effect For Surface Mount Devices: A Design For Reliability PerkinElmer Earl Vincent B. Lagsa	Waste Energy Utilization And Elimination Design For High Energy Demand Production Expansion Toshiba Gilbert P. Lutero
300 PM	BREAK	BREAK	BREAK	BREAK	BREAK
330 PM	Introduction of An Interactive HMI Software Into An Obsolete Shield Bend Machine For Small Outline Transistor VISHAY Rolando C. Espiritu Rio A. Tejada Sonny F. Santos	Test Efficiency Improvement Through Single Amplifier Configuration NXP Allan P. Mañago Myra C. Bagadiong Romel A. Trucilla	Fabrication of Micro-inductors and Micro- capacitors for Radio Frequency Applications UP Diliman Condensed Matter Physics Laboratory (CMPL)- National Institute of Physics (NIP) Microelectronics & Microprocessors Laboratory Department of Electrical and Electronics Engineering (DEEE)	F602 TOC Time Check Error Reduction IMI Dennis P. San Juan	Optimization of Compressed Air System By Reducing Compressed Air Pressure NXP Felomino A. Palino Jr.
400 PM	Breakthrough Improvement On Diebond Quality Through Equipment Optimization NXP Eufrocina L. Aranda	Parametric Functional Tester Signal Correction To Arrest Test Escape and Force Binning ON Semi Peter D. Casapao Ariel D. Caraig Francis F. Galauran	9.5 mm Slim Type Model Final Pass Yield Improvement: Six Sigma Way Of Doing Things IMI Ermilito R. Corpuz	24 ORAS Automatic Temperature Monitoring System NXP Joel N. Jaducana Myra C. Bagadiong Jenesis L. Lapira	Multiplex Interface Design Of Desktop Loader PC: A Solution In Reducing Test Equipment Power Consumption and Breakdown Toshiba Nusurudin A. Tahal Sancho O. Revicente / Rommel R. Patao

DAY 2: ANTS
Friday, 05 June 2009

TIME	SESSION A SMX Meeting Room 2&3	SESSION B SMX Meeting Room 4&5	SESSION C SMX Meeting Room 6	SESSION D SMX Meeting Room 8&9	SESSION E SMX Meeting Room 9
	SEMICONDUCTOR MANUFACTURING SYSTEM	PRODUCT & TEST TECHNOLOGY	PRODUCT & TEST TECHNOLOGY	ESD FORUM	ESD FORUM
	Moderators: Earl Vincent Lagsa Dr. Bernie Redoña	Moderators : Jimmy Apolinar Jojo Esmeria	Moderators : Dr. Terence Lacuesta Dr. Leon Payawan		
800 AM	BREAK	BREAK	BREAK		
900 AM	Lead-Lag Flow Dynamics on Thin Package with NiPdAu Frames ON Semi Marvin V. Picardal Onofre Boncodin	Understanding Test Handler Thermal Kit Performance: Key To Preventing Burn-In Thermal Runaway Issues for DSPS Devices TIPI Jonathan D. Mondero Christian Argon G. Aranas Jojo B. Yllana	Use Of Low Level Test Analysis For DVD-RAM Aging Test Of Optical Disc Drives IMI Robert R. Panopio Ronnie M. Faigao		
930 AM	Introduction Of New Stripping Solution To Address Plating Yellowish Discoloration SANYO Semiconductors Glenn D. Arruejo Melissa M. Oribello Rodolfo U. Sotto	Automotive Camera Applications IMI Juan Paolo R. Asis	Smart Bench Board For Silicon Verification Using Programmable System On Chip Cypress Edmon B. Belisario		
1000 AM	Qualification of Final Forming Punch and Anvil (New Material From High Speed Steel To Carbide) To Cater Both Tin Lead and Pre-Plated Leadframe ST Microelectronics Jeric G. Oyong Hannibal B. Buclatan Rolando N. Salazar	OSC 50 Phase Error And Duty Cycle Testing Using An RC Integrator Cypress Julius Paolo R. Servigon Melvin A. Damot	Optical Pick-Up Test Yield Improvement Through Six Sigma DMAIC Approach IMI Bobeth H. Araño		
1030 AM	Executing Flawless Launch of NZX Zener Series Using Business Creation Management Approach NXP Espie A. Alido Gil C. Espiritu Obet C. Sullera	Characteristics Of Tin Plating For Recovery Of Worn Out IC Test Contact Finger ON Semi Marvin V. Picardal Sammy Suaverdez	Socket Life Exerciser Cypress Prospero M. Chan Joseph V. Sebastian Jade F. Chaluyen		
1100 AM	A Solution To Wirebond PR Problem on HUQFN Package ST Microelectronics Edgar Olaso Nelson Guerrero Conrado Adrian M. Villanueva	Correcting Lens Distortion Via Image Processing IMI Juan Paolo R. Asis	Implementing CID: A Breakthrough Solution For Hardware Contact Tracking TIPI Jonathan D. Mondero Kevin Tiernan Mike Guenther		
1130 AM	MTI MSS-816 Machine Control System - A Cost Effective Way To Address Blade Breakage Problem At SOD110 Product Sawing Process NXP	Analysing The Effect Of TDR On Common IO For Test Program Stability And Yield Improvement Cypress Jeffrey S. Meneses	An Investigation Of Zigbee's Wireless Mesh Capability IMI Oliver T. Ortega		

	Giovanni M. Covita Roberta M. Sera Eleazar O. Novenario				
1200	LUNCH BREAK	LUNCHBREAK	LUNCH BREAK		
130 PM	Resolution of Broken Stitch for Pre-Plated Leadframe ST Microelectronics Anthony Glenn G. Calasicas Alexander B. Angeles	Very Low Power Zigbee End Point Using Alternative RF Wakeup IMI Christopher Allen O. Rubis	Socket Pogo Pin Resistance Checker (SPPRC) Cypress Arnold M. Ibarrola Vener James T. Andal Prospero M. Chan		
200 PM	Industry Academe Technical Dialogue	Universal Burn-In Board Design: A Project To Reduce Cost And Improve New Product Introduction Cycle Time Cypress Samuel G. Navarro Aristotle M. Venturina			
230 PM	BREAK	BREAK	BREAK		
	Learning Session	Learning Session	Learning Session		
300 PM	Method for Generating High Contrast Images of Semiconductor Sites via One-Photon Optical Beam Induced Current Imaging and Confocal Reflectance Microscopy University of the Philippines Diliman Kalayaan Magno Mary Grace Bato	Application of Test Technologies in Product Development Electrical Electronics TUV SUD PSB Singapore Dr. Deng Junhong	Plasma Enhanced Chemical Vapor Deposition Method for Thin Film Titanium Nitride Coating University of the Philippines Diliman Melissa Camacho		
400 PM		FELLOWSHIP	NIGHT		

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ASEMEP NATIONAL TECHNICAL SYMPOSIUM

Event Program (Closing Ceremonies)

DAY 2: Friday, 05 June 2009

- 6:00 PM Awarding Ceremonies
Most Number of Delegates & Technical Papers Submitted
Best Paper Awards
IMI Excellence Award
Service Award (Outgoing ASEMEP BOD)
- 6:30 PM Fellowship Dinner for All
19th ANTS & ESD REGISTERED ATTENDEES
Location: *Claire Dela Fuente, directly behind SMX Convention Center, at San Miguel by the Bay*

19th
ASEMEP
NATIONAL
TECHNICAL
SYMPOSIUM



5th
PHILIPPINE
ELECTROSTATIC
DISCHARGE
FORUM